

Technical data sheet

Product description	Colourless, two-component, solvent-free, epoxy resin with very low viscosity.		
Application	• The possibility of embedding materials, graphics, stones, etc. • Possibility of pouring the material as a thick, transparent resin screed without fillers, • Material for use inside buildings as a construction and closing layer.		
Properties	• Very high adhesion between layers, • High degree of transparency/crystallinity, • High degree of gloss, • Good chemical resistance, • Good abrasion resistance, • Good mechanical parameters (hardness, bending strength, tensile strength), • Provides hydrophobic properties, • Very low viscosity, • Undetectable temperature peak, • Long curing time, • Low resin shrinkage, • Ease of application, • Frost resistance, • Versatility of applications.		
Physical properties of Siconofloor FORM			
Character	Component A modified epoxy liquid		
	Component B amine hardener		
Density (according to PN EN ISO 2811-2)	Component A	1.1409±0.008 g/cm³	
	Component B	0.9448± 0.01 g/cm³	
Colour and smell	Component A transparent and odourless		
	Component B liquid with a characteristic smell		
Hygiene tests	Meets requirements; No PZH approval for direct contact with food		
Curing time	Light loads after 72 h at 25°C		
	Full load capacity	10 days	
Practical consumption of the mixture	Strongly depends on the intended use, application technique, application conditions and the degree of roughness of the substrate.		
Viscosity (according to ISO 3219) for 25°C	Component A (SP03/RPM 30/E14.1)	170-500 mPa*s	
	Component B (SP 02/ RPM 100 /F14)	33-40 mPa*s	
Mechanical properties of Siconfloor Form			
Dust dry		72 hours at a temperature of 20°C	
ShA hardness (after 10 days)		90.4°	
ShD hardness		80.0°	
Application			
Preparation of the substrate	The substrate must have sufficient compressive strength (minimum 25 N/mm²). The surface must be even, slightly rough, strong and dry, free from loose particles. The “pull off” test should not give a result below 1.5 N/mm². If in doubt, a reference field should be made. Fragments of the substrate of insufficient strength, cement laitance and fragments contaminated with oils or other separating substances must be removed mechanically, e.g. by shot peening, grinding or milling. The substrate must have open pores before the material is applied. Immediately		
Application conditions	The temperature of the substrate should be +5–30°C. It should be remembered that the lower the temperature, the longer the curing process of SICONOFLOOR FORM. Ambient temperature should be +5–30°C. Substrate humidity should be max 5%. Relative air humidity should be a maximum of 80%. The temperature of the substrate and uncured flooring must always be 3°C above the dew point temperature. Freshly applied SICONOFLOOR FORM must be protected against moisture and direct exposure to water for at least 24 hours from the completion of application. The formation of laitance discolouration on the surface indicates contact of fresh material with moisture resulting in divergence in the properties of the final product from the properties declared by SICON. If artificial heating is required, do not use gas, oil, paraffin or other fossil fuel heaters. During the operation of such devices, large amounts of water and carbon dioxide in the form of water vapour		
Application methods	Pre-mix component A and then add component B, mix the components until a homogeneous consistency is obtained, but not less than 3 minutes. The mixing ratio of Component A and Component B is shown on the packaging and must not be changed. Changing the proportions will result in a product with properties different from those declared by the Manufacturer. Mixing for too long may cause air entrainment and should therefore be avoided. To mix the resin, use a low speed electric stirrer (300+400 rpm) or other equipment designed for this.		